



PART NO. : TD66-1006KRL

16PIN DIP ISOLATION MODULE

MEET REQUIREMENTS OF 10BASE-T
FILTERLESS SOLUTION

RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE WAVE SOLDERING
PROCESS FOR THROUGH HOLE COMPONENTS

OPERATING TEMPERATURE 0/70°C

ELECTRICAL SPECIFICATIONS @25°C

URNS RATIO

P1-3:P16-14

2CT:1CT $\pm 3\%$

P6-8:P11-9

1CT:1CT $\pm 3\%$

OCL (100KHz,50mV)

P1-3,P6-8

150 μ H min

Cw/w P1-16

10pF max

P6-11

15pF max

LL P1-3

1.0 μ H max

P6-8

0.3 μ H max

DCR P1-3

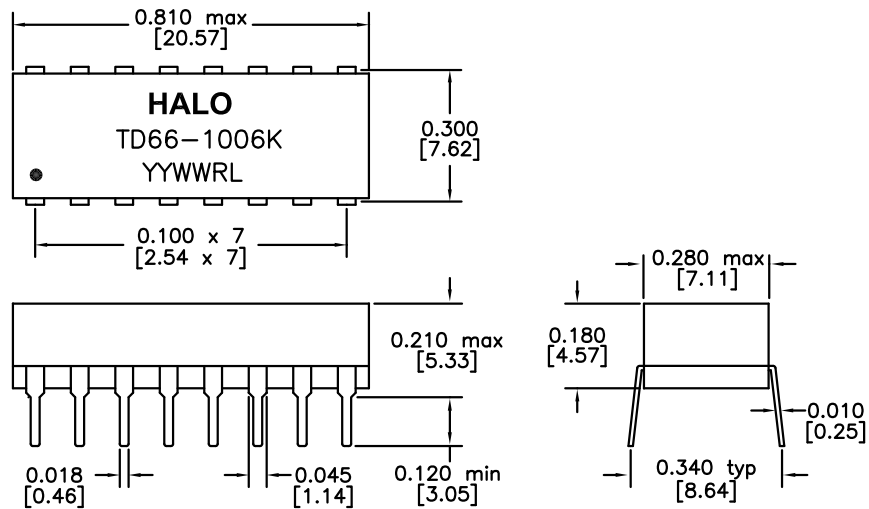
0.35 Ω max

P6-8

0.35 Ω max

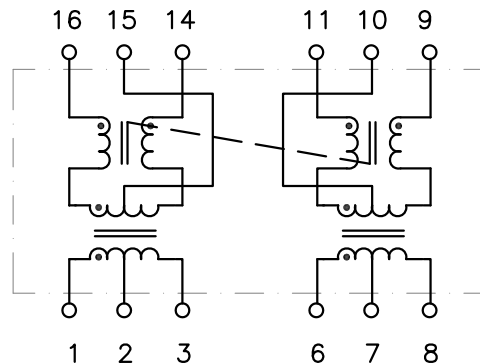
ISOLATION

2,000Vrms



DIMENSIONS: Inch [mm]

TOLERANCES: ± 0.005 INCH IF NOT SPECIFIED



HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE 16PIN ISOLATION MODULE

FOR 10BASE-T

PART NO. TD66-1006KRL

SCALE NONE

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SIGNATURES

DRAWN LI ZHI ZHONG

CHECKED LEI KEONG

APPROVED PETER LU

FILE TD66KRL.DWG

DATE

5/28/15

6/6/15

6/6/15

REV.

A

B

DESC.

FIRST ISSUE

PROD. RELEASE

